

是德科技感恩月

有趣 有料 有惊喜



科技改变生活

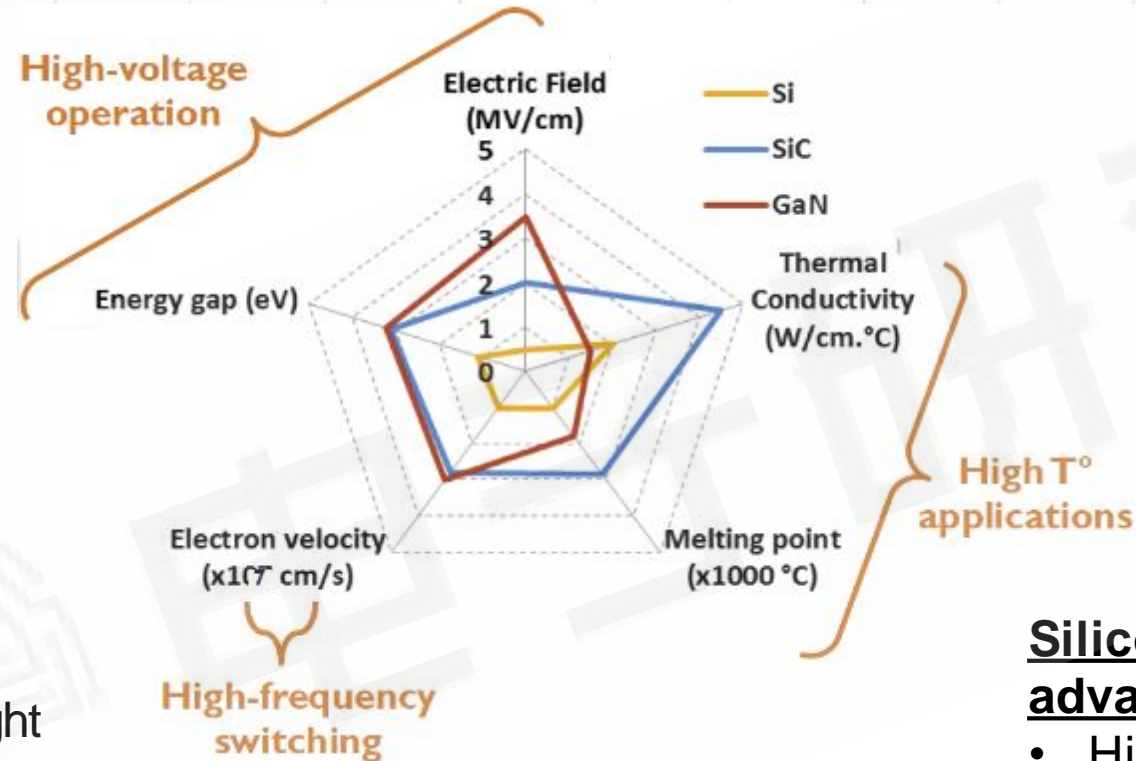


4x SMALLER
6x LIGHTER



New power semiconductor technology emerges

Wide Bandgap Devices (WBG) – Silicon Carbide (SiC) & Gallium Nitride (GaN)



Gallium Nitride (GaN) advantages over Si

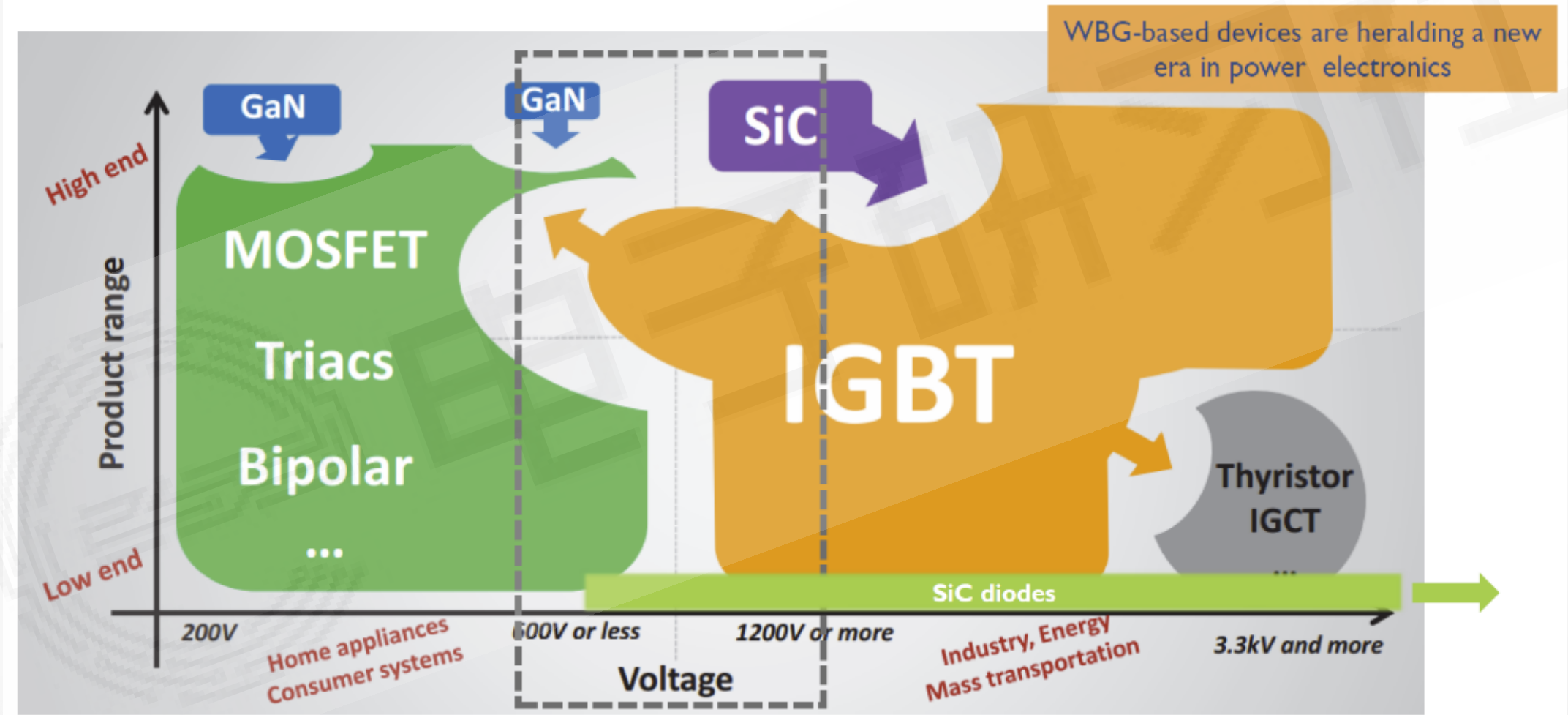
- Very fast switching frequency
- Compactness and weight reduction
- 3X higher bandgap of Si
- Reduction of conduction and switching loss
- Low $R_{ds(on)}$

Silicon Carbide (SiC) advantages over Si

- High Temperature Operation
- > 2X thermal conductivity of Si
- 3X higher bandgap of Si
- 10X higher breakdown field
- Up to 1000X lower $R_{ds(on)}$

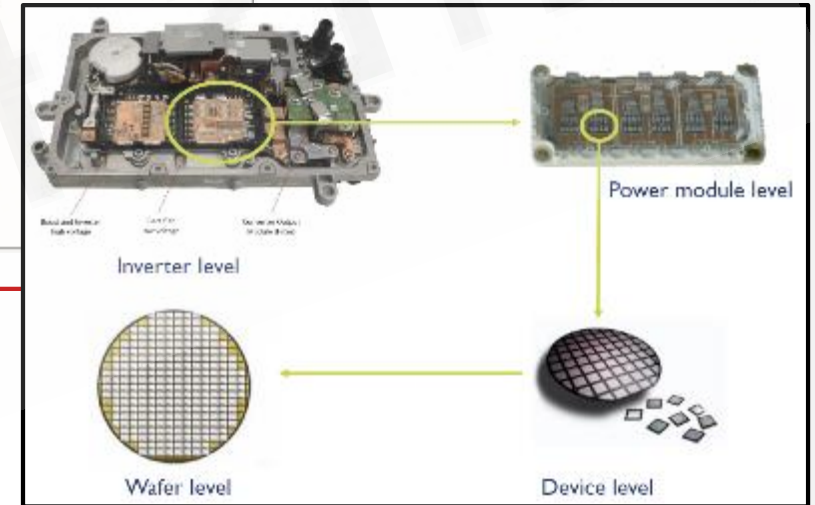
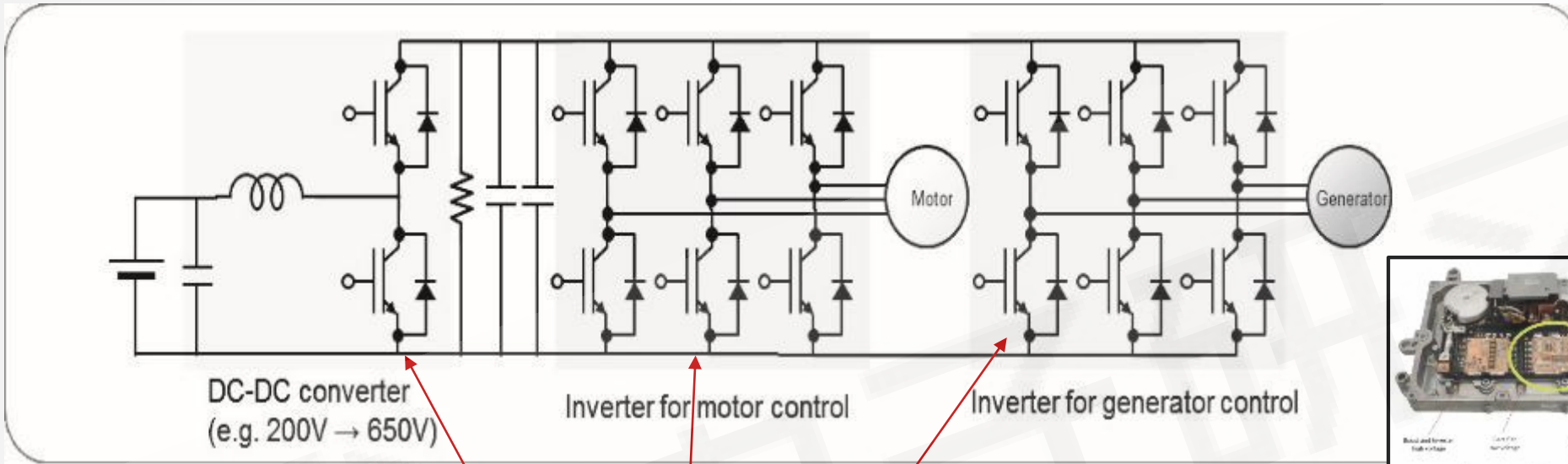
Wide Band Gap Market

Power Device technology positioning by 2023

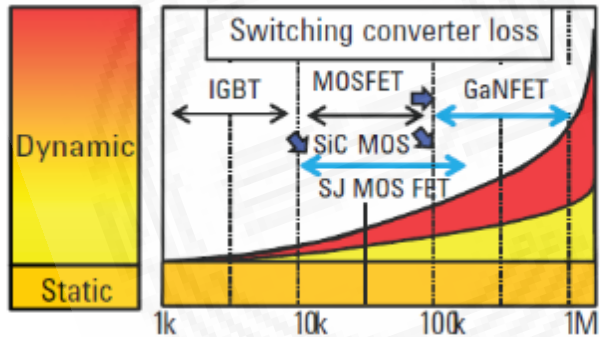


Power converter design

Switching power conversion



Power device loss vs Switching frequency



$$P(\text{drive loss}) = f * Q_g * V_{gs}$$

$$P(\text{Switching loss}) \propto f * (V * I * \Delta T), \quad \frac{1}{2} * C_{oss} * V^2$$

$$\propto R_g, C_{rss}$$

$$P(\text{Conduction loss}) = R_{on} * I_{rms}^2$$

WBG device employment for power circuit



WBG properties

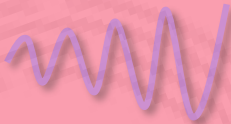
Lower power loss



Better conversion efficiency =
Smaller / Lighter cooling system



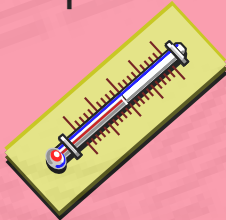
Higher frequency operation



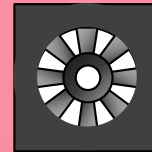
Smaller passive circuit components



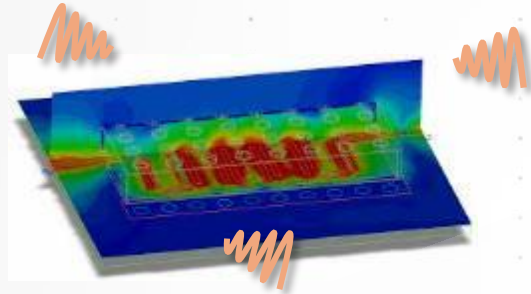
Higher temperature operation



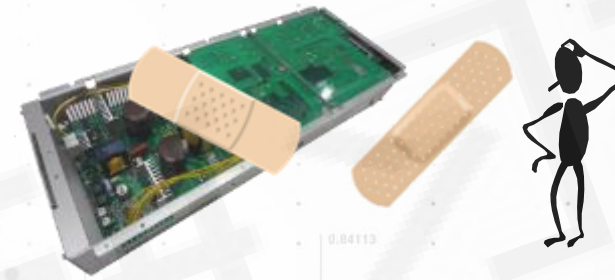
Smaller / Lighter / Sealed cooling system for
harsh environment use, (e.g. excavator use)



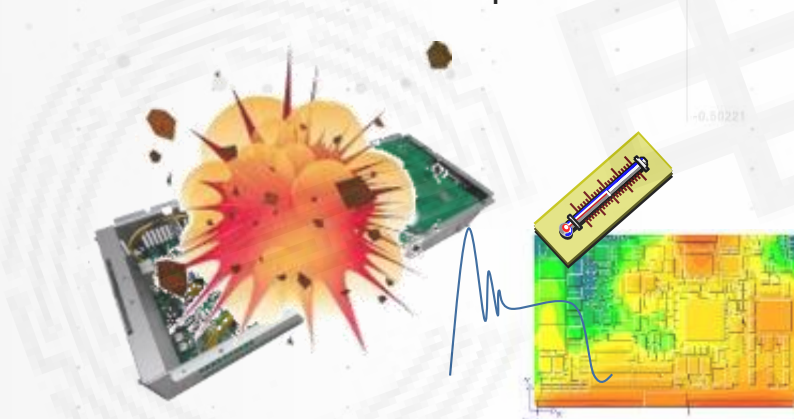
Challenges in power circuit design



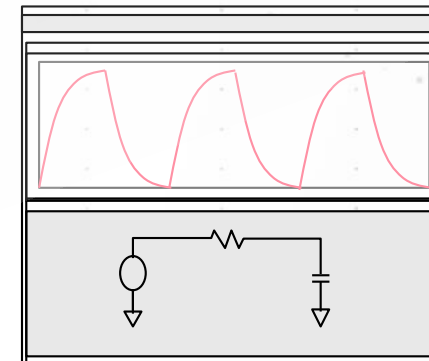
High switching frequency along with high frequency components in waveform causes unexpected EMI



High switching frequency and associated surge/ringing causes malfunction

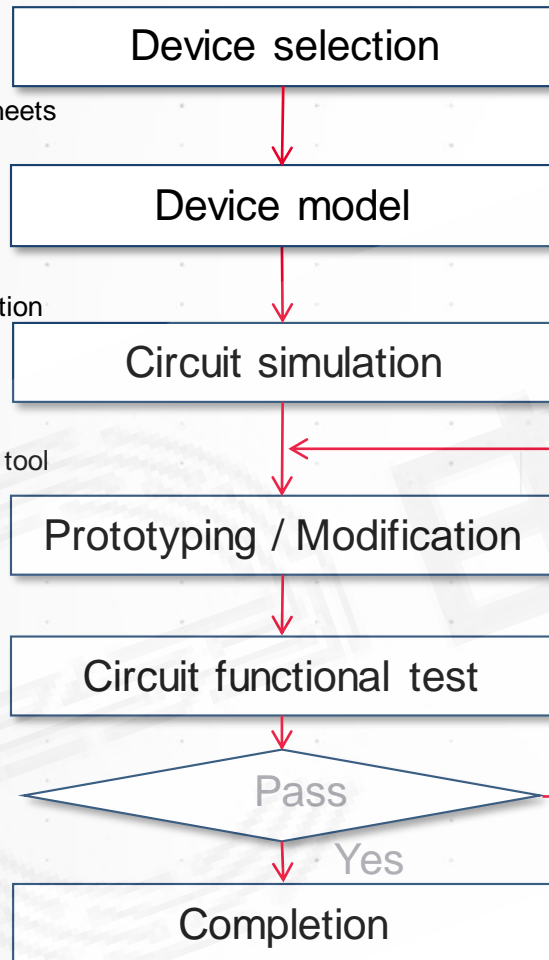


Prototype circuit explosion due to unexpected surge and heat generation

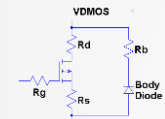


Lack of power circuit simulation tool. Conventional tool may work for low frequency circuit but not for WBG device circuit

Before & After Our Solution



Unreliable vendor datasheets



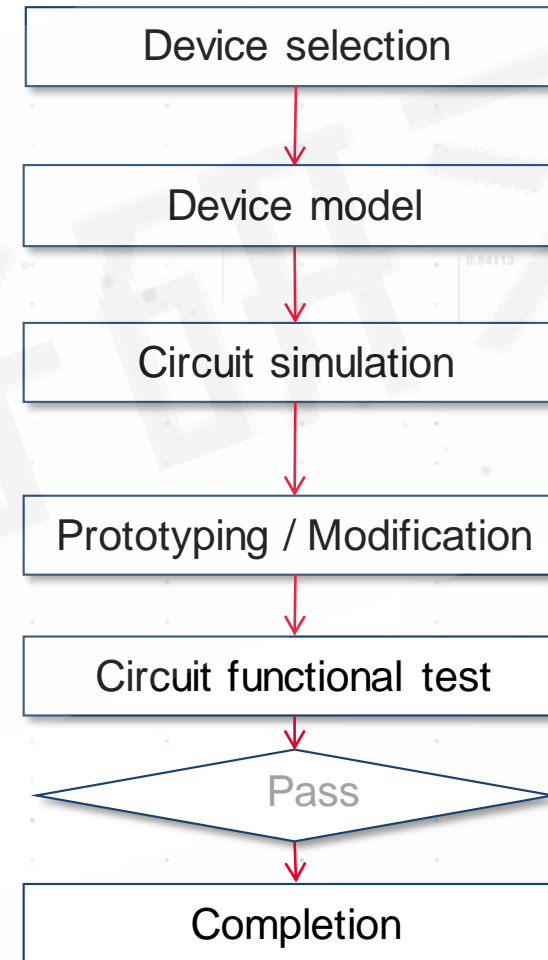
poor device model to produce trustable simulation



Cheap & inaccurate SIM tool



Repeat prototyping



Keysight instruments

Sure selection & accurate data extraction for model creation

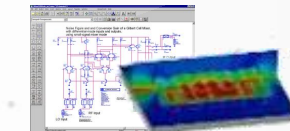


Keysight PE model generator



Measurement driven polynomial model based on a math model

Keysight ADS/EMPro/Momentum



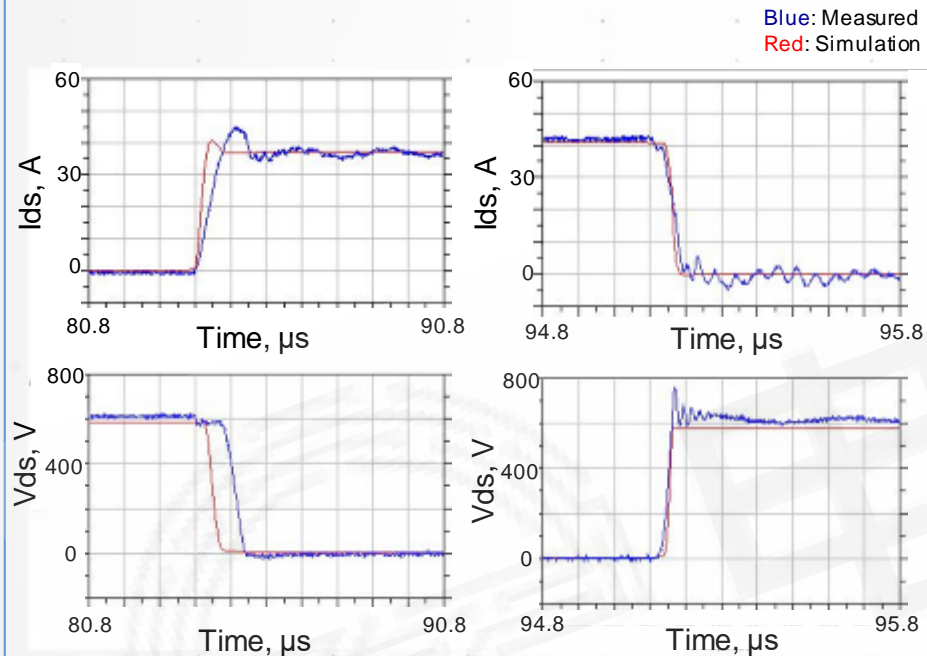
Reliable time domain & EM simulation based on reliable model



Conventional simulation vs. New Keysight simulation method



Simulation with a conventional model



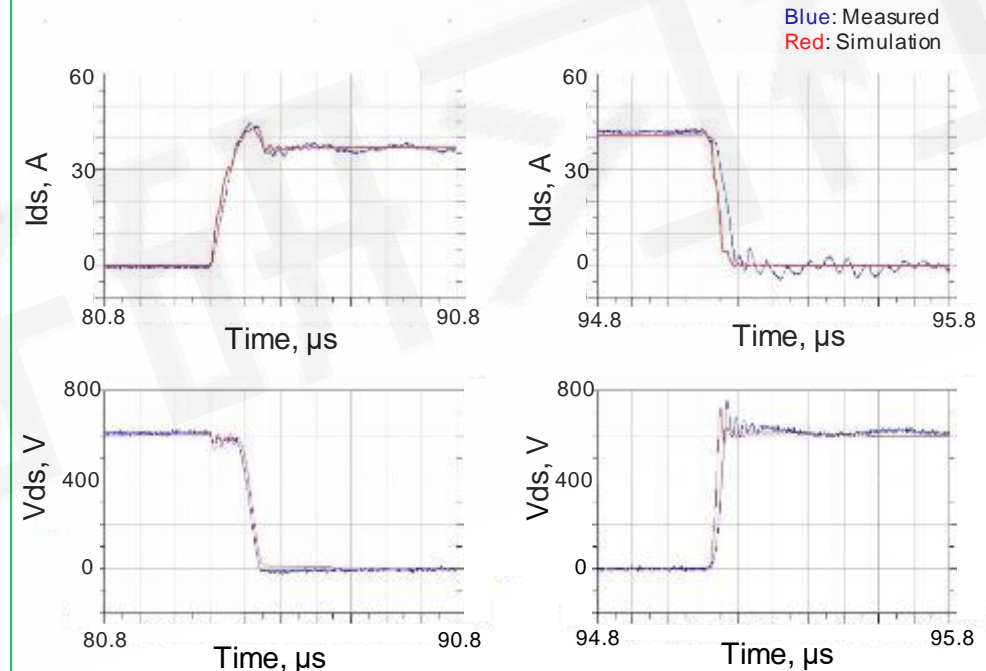
Waveforms don't match.

- Ringing/overshoot are not simulated (flat line)
- Timing deviation
- Slew rate deviation

Exact waveform match is critical for noise calculation as waveform contains high frequency components



Simulation with the Keysight math model



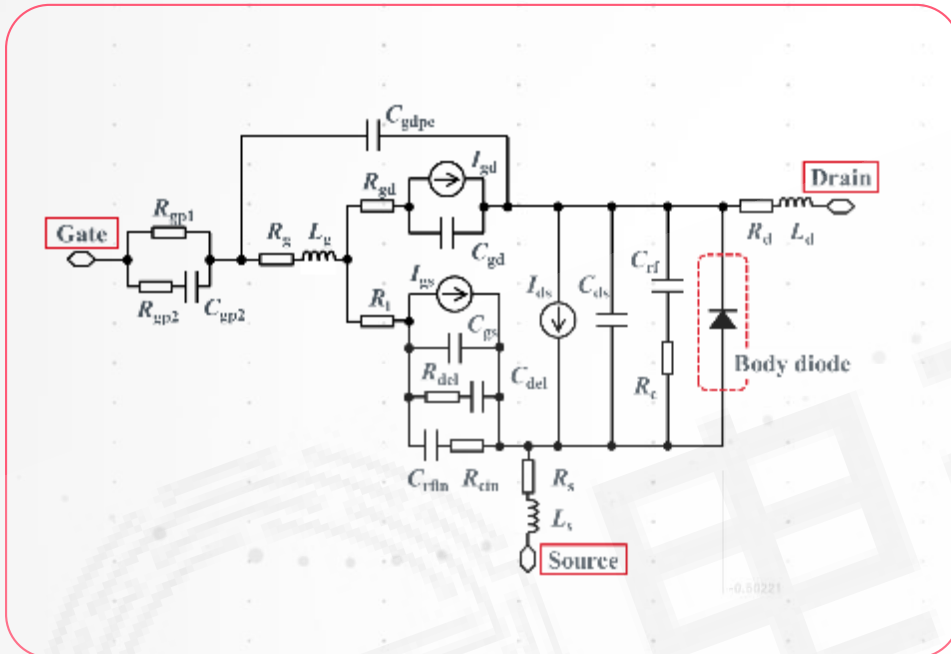
Excellent matching between simulation and measurement

Source: "Measurement Methodology for Accurate Modeling of SiC MOSFET Switching Behavior over Wide Voltage and Current Ranges", H. Sakairi, et. al., IEEE Trans on Power Electronics early access,

What makes this improvement?

What are different? (1)

DEVICE MODEL



Added body diode to better fit to SiC

$$\tanh\left(\left(\text{Lambda1} \times \tanh(1 + \text{Lambda2} \times V_{gs})\right) \times V_{ds}\right)$$

Added V_{gs} , V_{ds} dependent parameter to drain current equation to better represent unsaturated drain current

$$Q_{gs} = (C_{gspi} + C_{gs0} \times \tanh 02) + (C_{gspi} + (C_{gs0} \times \tanh 01 + C_{gs0i} \times \tanh 1i) \times \tanh 02)$$

$$\tanh XX(i) = 1 + \tanh(A + B \times V_{gs} + C \times V_{ds})$$

Added tanhXX to express a positive bias dependence on charge equation

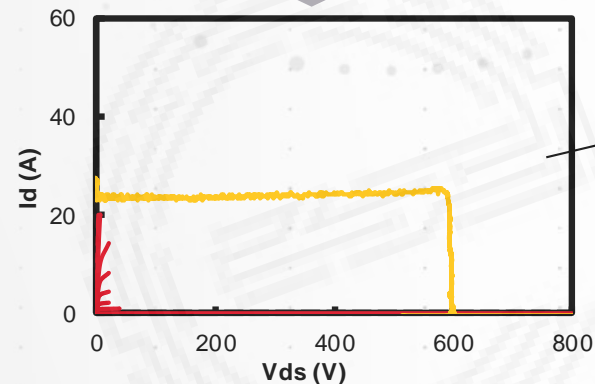
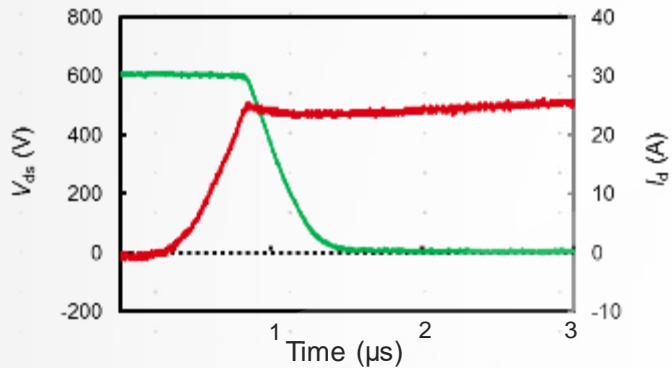
- Modified popular Angelov GaN
 - To represent SiC or GaN behavior better
 - Independent of device physics parameters (e.g. T_{ox}) → Everyone (e.g. circuit designer) can use it

Source: "Measurement Methodology for Accurate Modeling of SiC MOSFET Switching Behavior over Wide Voltage and Current Ranges", H. Sakairi, et. al., IEEE Trans on Power Electronics early access,

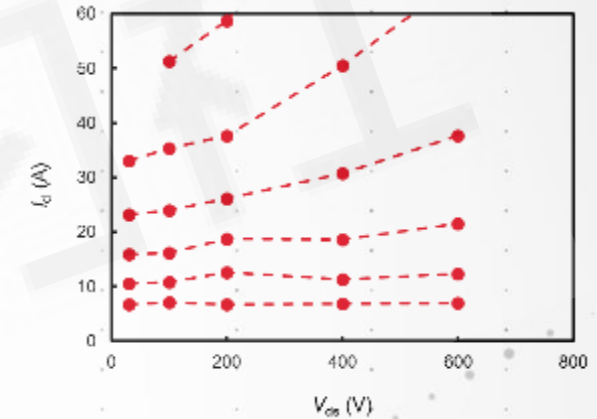
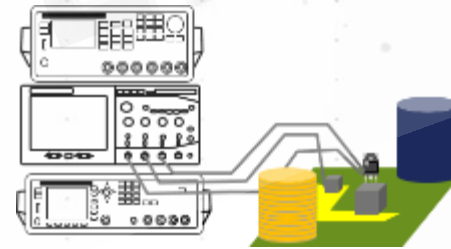
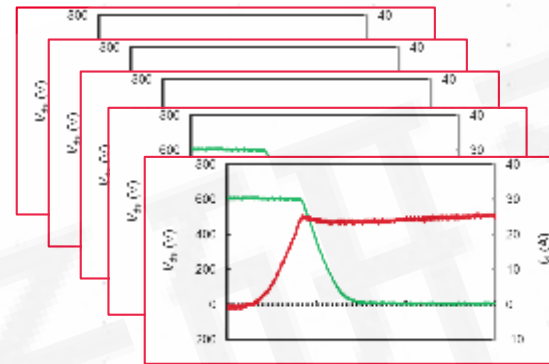
What are different? (2)

EXTENSIVE MEASUREMENT TO MAKE THE MODEL REPRESENTATION SIGNIFICANTLY BETTER

(A) Wide range IV using double pulse test



IV curve with conventional test equipment doesn't cover switching trajectory



Wide range IV curve

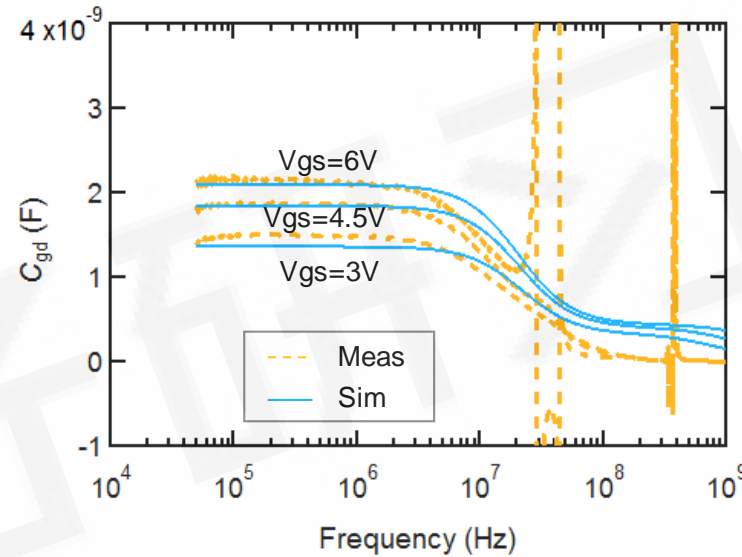
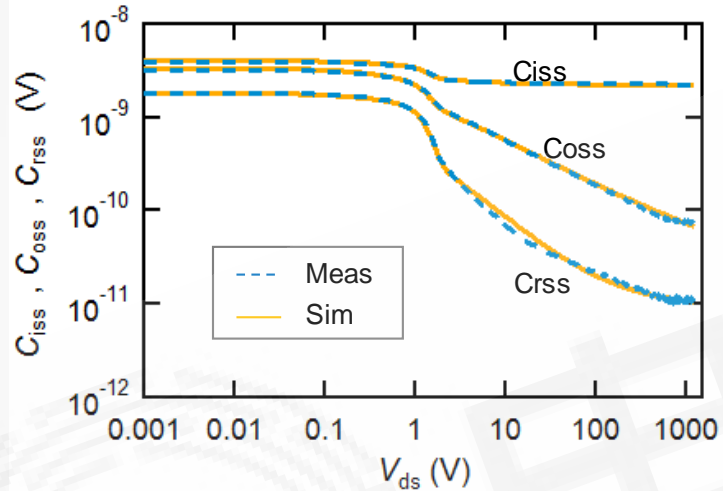
- Utilize double pulse test system to obtain wide enough IV curve to cover switching trajectory

Source: "Measurement Methodology for Accurate Modeling of SiC MOSFET Switching Behavior over Wide Voltage and Current Ranges", H.Sakairi, et. al., IEEE Trans on Power Electronics early access,

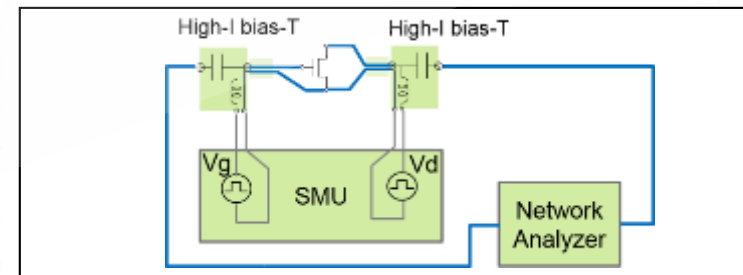
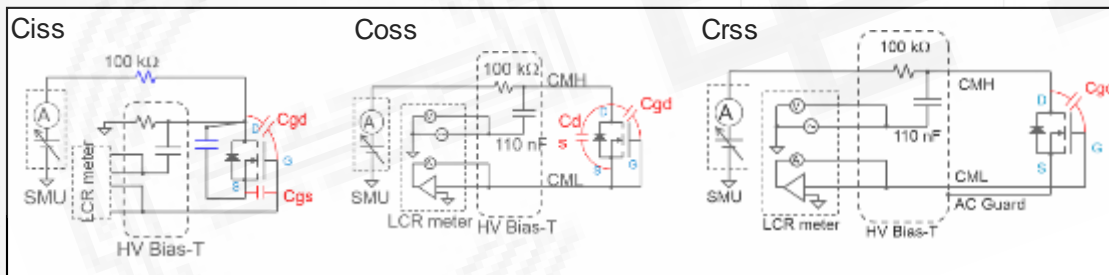
What are different? (3)

EXTENSIVE MEASUREMENT TO MAKE THE MODEL REPRESENTATION SIGNIFICANTLY BETTER

(B) Inclusion of CV (both off-state & on-state)



Discontinuous measurement points seen beyond 10MHz are considered to be caused by oscillation due to parasitic and stray inductance associated with measurement circuit. Therefore, simulation didn't include those points.



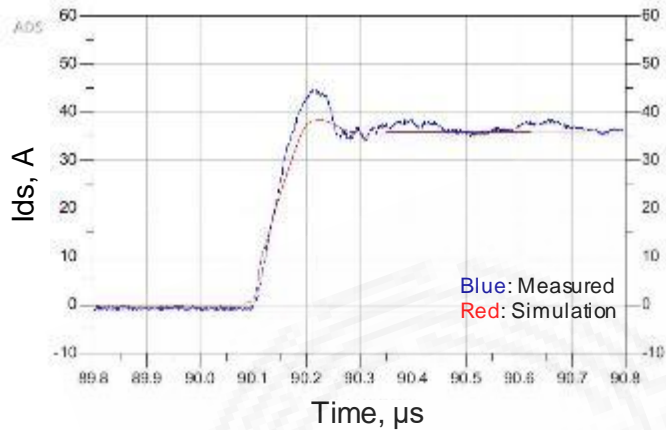
- Inclusion of non-linear characteristics is critical to represent device physical phenomena better

Source: "Measurement Methodology for Accurate Modeling of SiC MOSFET Switching Behavior over Wide Voltage and Current Ranges", H. Sakairi, et. al., IEEE Trans on Power Electronics early access,

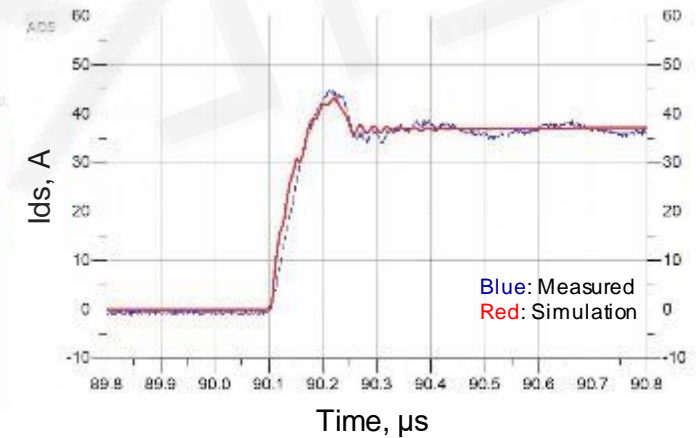
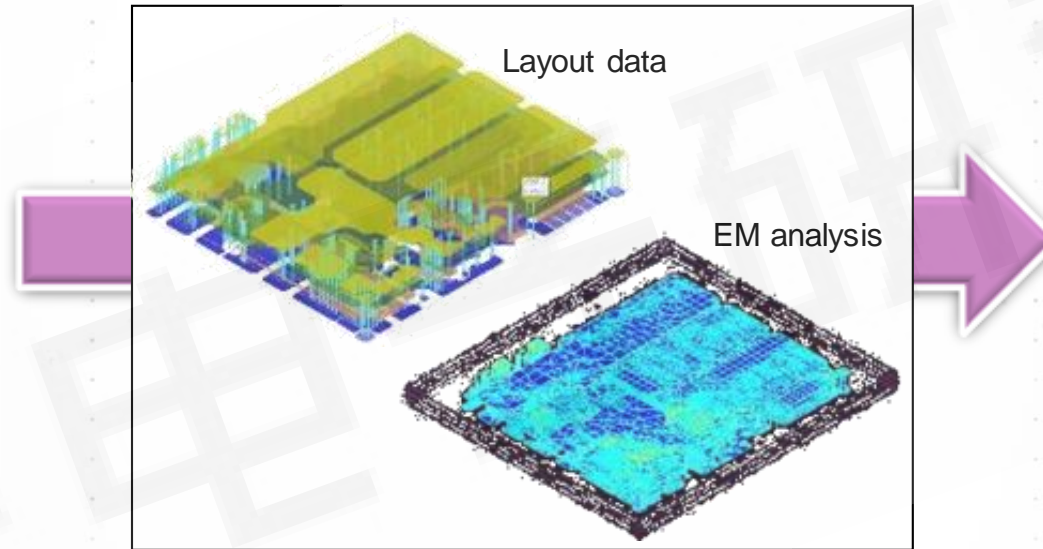
What are different? (4)

EMPLOYMENT OF ELECTROMAGNETIC ANALYSIS

To use simulation software that performs not only time domain analysis but also incorporate electro-thermal and layout distribution effects



Improved device model without extensive EM simulation



Improved device model with extensive EM simulation

Electromagnetic simulation using board layout information as well as inclusion of s-parameters measured on DUT, the simulation of circuit operation becomes significantly better.

Source: "Measurement Methodology for Accurate Modeling of SiC MOSFET Switching Behavior over Wide Voltage and Current Ranges", H. Sakairi, et. al., IEEE Trans on Power Electronics early access,

Solution to realize this vision



PD1000A software

PD1000A

Test solutions

- B1506A (B1505A)**
- DPT PD1500A**
- ENA E5080A**
- ENA w SMU**

Measurement data

I-V (*2)

C-V

Zero-bias s-parameters

On-state C-V through S-parameters (*2)

Keysight mathematical model

W8598BP/BT Simple-use PEMG

PEMG: Power Electronics Model Generator

Model parameters

Circuit/EM simulation with significantly improved accuracy

ADS / EMPro / Momentum

元器件测试方案_B1506A功率器件分析仪

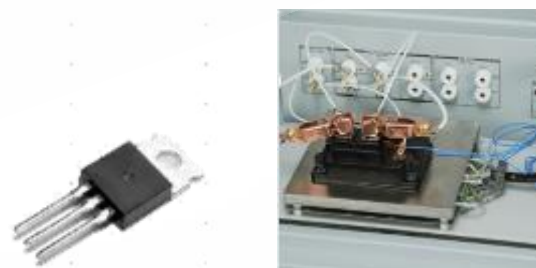


全面的测试参数:

分类	参数
阈值电压	V(th)、Vge(th)
传输特征	Id-Vgs、Ic-Vge、gfs
导通电阻	Rds-on、Vce(sat)
栅极泄漏电流	Igss、Iges
输出泄漏电流	Idss、Ices
输出特征	Id-Vds、Ic-Vce
击穿电压	BVds、BVces
栅极电荷	Qg、Qg(th)、Qgs、Qgd、Qsw、Qsync
栅极电阻	Rg
器件电容	Ciss、Coss、Coss_eff、Crss、Cgs、Cgd、Cies、Coes、Cres
切换参数	Td(通)、Td(断)、Tr、Tf; 计算值。
切换损耗	特定频率上的驱动损耗/切换损耗 特定占空比下的传导损耗

宽广的测试范围:

- 电流 1500 A
- 电压 3 kV
- -50 ° C 至 +250 ° C 快速热测试



元器件测试方案_B1506A功率器件分析仪



4. 执行测试

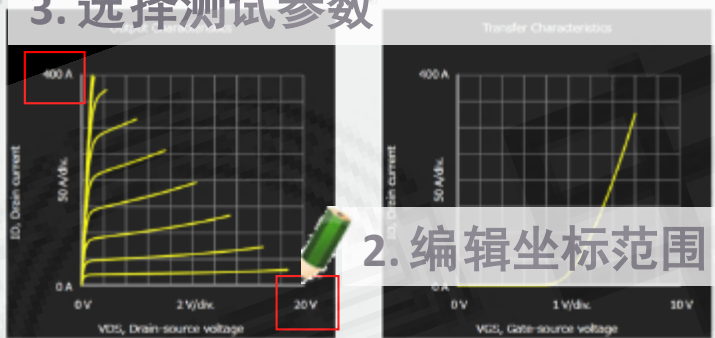
1. 设定测试条件

Symbol	Parameter	Test Conditions	Min.	Act.	Max.	Unit	Note
V_{DS}	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100\mu A$	100	121		V	
$V_{GS(th)}$	Gate Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 3mA$	2.0	4.0	4.5	V	
I_{DSS}	Drain Off Leak Current	$V_{GS} = 0V, V_{DS} = 100V$	1.0	10.0	100.0	μA	
I_{GSS}	Gate Leak Current	$V_{GS} = 20V, V_{DS} = 0V$	10.0	100.0		nA	
$R_{DS(on)}$	Drain to Source On-state Resistance	$V_{GS} = 10V, I_D = 30A$	5	11		mOhm	
R_g	Gate Resistance	$f = 1MHz$	0.5	1.0		Ohm	

详细的测试参数

Min.	Act.	Max.	Unit	Note
100	121		V	
2.0	4.7	4.5	V	
	1.0	10.0	μA	
	10.0	100.0	nA	
	5	11	mOhm	
	0.5	1.0	Ohm	

3. 选择测试参数



Gate Charge Characteristics

Switching Waveform

MARKERS:

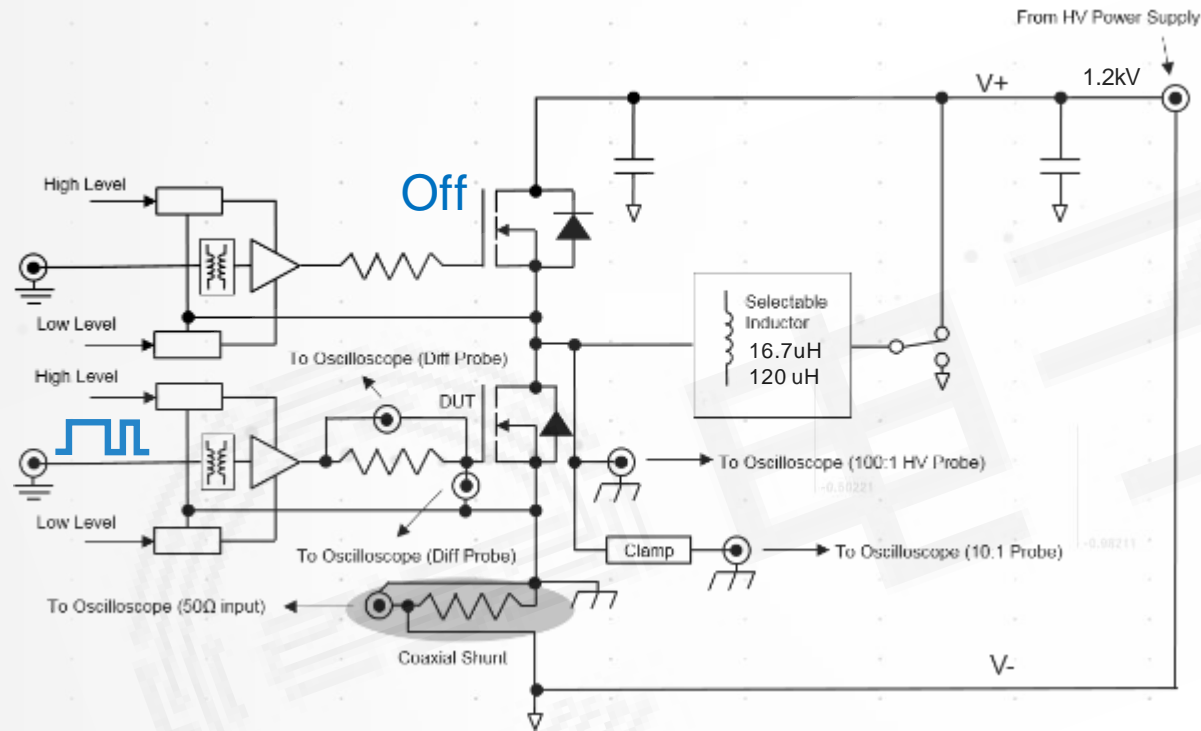
- $V_{GS(th)}$
- $V_{GS(pl)}$
- $V_{GS(off)}$
- Q_{gs}
- Q_{gd}
- $Q_{g(th)}$
- $Q_{g(on)}$

Symbol	Value	Unit	Description
$V_{GS(pl)}$	6.169	V	gate plateau voltage
Q_{gs}	22	n	gate-source charge
Q_{gd}	72	n	gate-drain charge
$Q_{g(th)}$	15	n	gate-source threshold charge
$Q_{g(on)}$	172	n	on-state gate-source charge
$C1$	3.636	F	$Q_{gs}/(V_{GS(pl)}-V_{GS(off)})$
$C2$	8.83	n	$(Q_{g(on)}-Q_{gs}-Q_{gd})/(V_{GS(on)}-V_{GS(pl)})$
$S1$	275	m	slope 1 (V/nC)
$S2$	113	m	slope 2 (V/nC)

What is double pulse test?

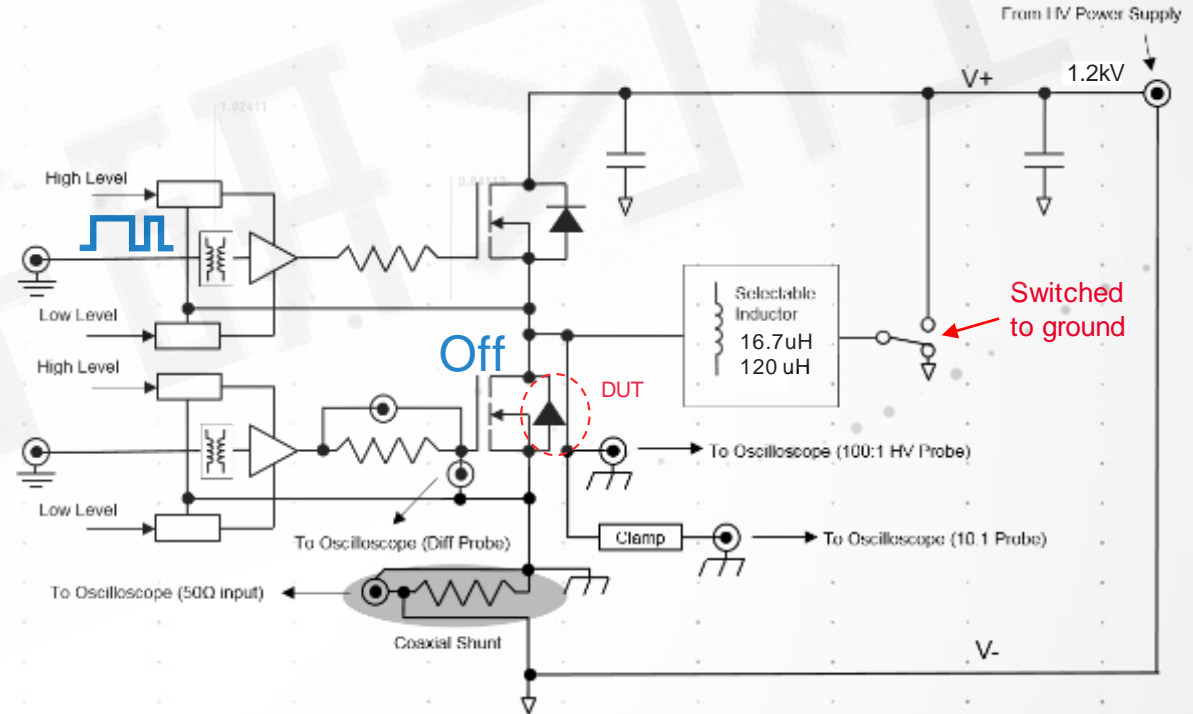
TO EVALUATE POWER DEVICE DYNAMIC BEHAVIOR

Switching characterization (*1)



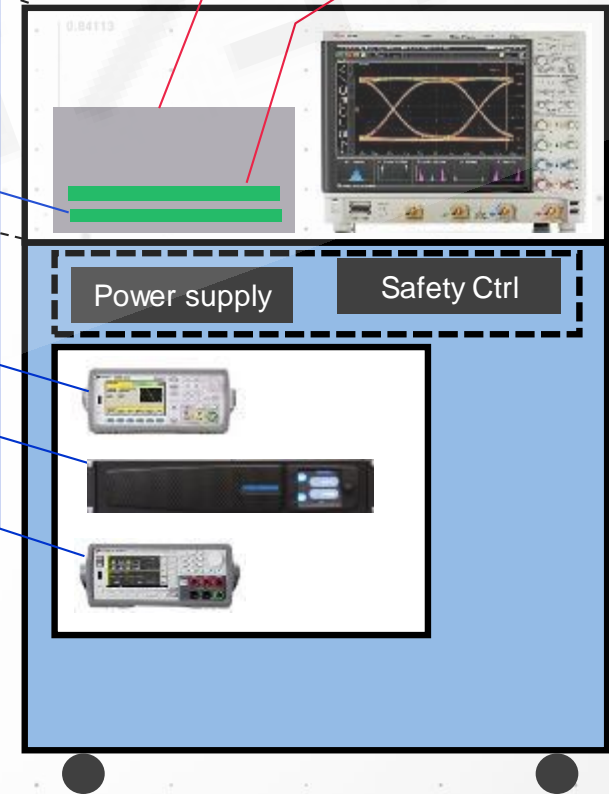
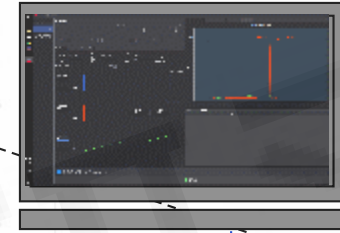
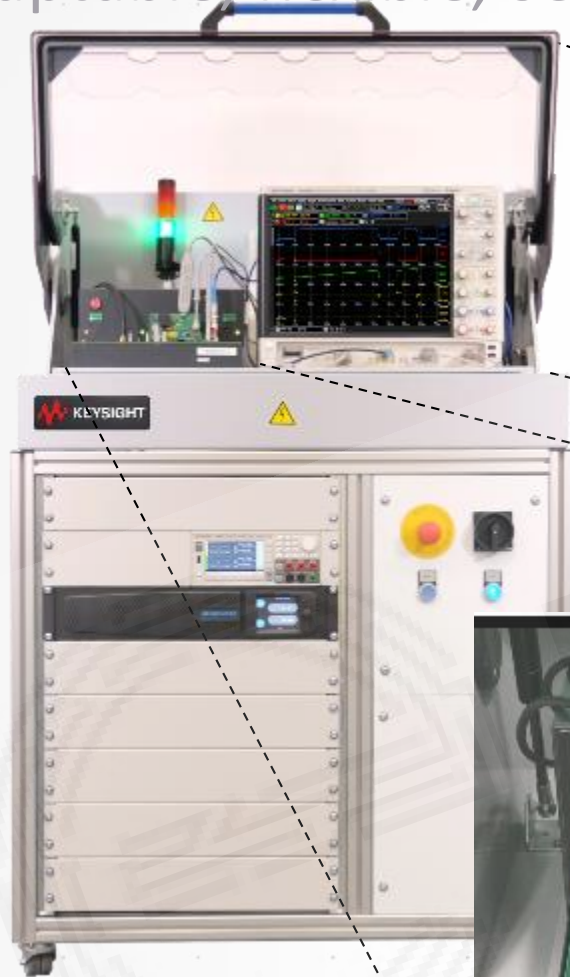
(*1) For gate charge measurement, the low side gate driver is exchanged to the one with high R_g .

Reverse recovery



Modular architecture concept

Adaptable, flexible, semi-automatic and safe test station



Fixture

Keysight PD1500A

DYNAMIC POWER DEVICE ANALYZER/DOUBLE PULSE TESTER

- Clean & automated turn-key solution with safe test fixture
 - Covers various waveform characterization & parameter extraction with semi-automated operation
 - Switching / Reverse recovery / Gate charge / High power IV
 - (coming soon) Short circuit, UIS avalanche test
 - Automatic temperature control (room temperature to +150C)
 - Operator & resource safety (protection mechanism)
- Adaptable to various DUTs
 - Fast, low-parasitic, generic gate-driver with variable voltages (e.g. -10V to +29V, ns edge)
 - Modular architecture
 - Replaceable double pulse PCB for different apps.
 - Controllable capacitor bank & switchable inductor (16.7uH, 120uH)
- Repeatable, Reliable, Accurate measurement
 - Auto Calibration /De-skew / compensation for better accuracy
 - Shunt de-embedding

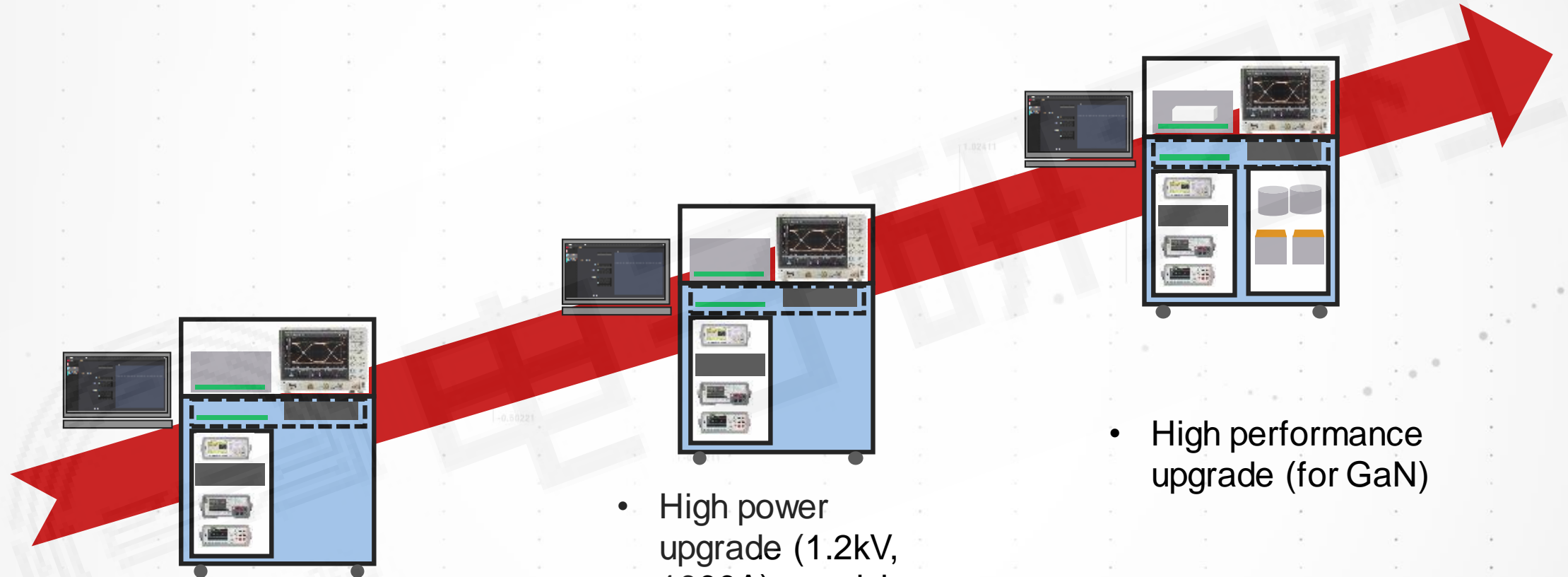


Applications



Parameter / Characteristics	Symbol	Basic	Clamp	Reverse recovery	Gate charge	DF		
Turn on delay time $t_d(\text{on})$	$t_d(\text{on})$	X	X					
Turn on rise time	t_r	X	X					
Turn on time	t_{on}	X	X					
Turn on energy	$e(\text{on})$	X	X					
Turn off delay time $t_d(\text{off})$	$t_d(\text{off})$	X	X					
Turn off rise time	t_f	X	X					
Turn off time	t_{off}	X	X					
Turn off energy	$e(\text{off})$	X	X					
di/dt	dv/dt	X	X					
dv/dt	di/dt	X	X					
On resistance	$R_{\text{ds(on)}}$		X					
Switching characteristics	I_d vs. t	X	X		X	X	X	X
Switching characteristics	V_{ds} vs. t	X	X		X	X	X	X
Switching characteristics	V_{gs} vs. t	X	X		X	X	X	X
Switching characteristics	I_g vs. t	X			X	X		X
Switching characteristics	Clamped V_{ds} vs. t		X					
Switching characteristics	e vs. t	X	X					
Switching locus	I_d vs V_{ds}	X	X					
Reverse recovery time	t_{rr}			X				
Reverse recovery charge	Q_{rr}			X				
Reverse recovery energy	E_{rr}			X				
Maximum reverse recovery current	I_{rr}			X				
Reverse recovery current characteristics	I_d vs. t			X				
Total gate charge	Q_g				X			
Threshold gate charge	$Q_{\text{gs(th)}}$				X			
Plateau gate charge	$Q_{\text{gs(pl)}}$				X			
Gate drain charge	Q_{gd}				X			
Gate charge curve	V_{gs} vs. t				X			
Derived transfer characteristics	I_d vs. V_g					X		
Derived output characteristics	I_d vs. V_d					X		
Parasitic turn on V_{gs}	$V_{\text{gs(para)}}$							X
Parasitic turn on peak I_d	$I_d(\text{para})$							X

Modularity allows for Upgradeability



Si, SiC (1.2kV, 200A)

- High power upgrade (1.2kV, 1000A) - module
- Avalanche Test
- Short Circuit Test

- High performance upgrade (for GaN)

是德科技功率器件测试方案

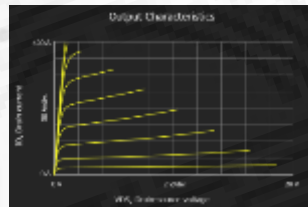


2kV CAT1, 1kV
CAT III & 400 MHz

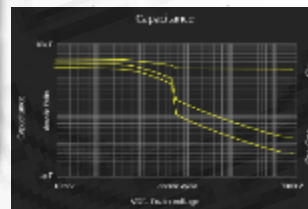
Keysight PD1000A Power Device Measurement System for Advanced Modeling

B1506A Power Device Analyzer

- I-V 3kV, 20A/500A/1500A models
- C-V up to 3kV (Ciss, Coss, Crss, Cox)
- Automated and easy to use operation
- Automated thermal up to +250°C
- Pulse width down to 10us



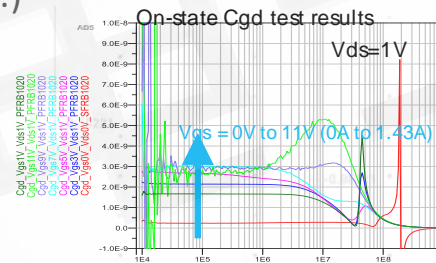
IV



CV up to 3kV

S-parameter measurement

- 9kHz – 4.5GHz
- High current bias-T (5A/42V)
- Automated and easy to use operation
- LCR extraction (Stray L, biased Crss, Rg, etc.)



Extracted Crss from s-parameters

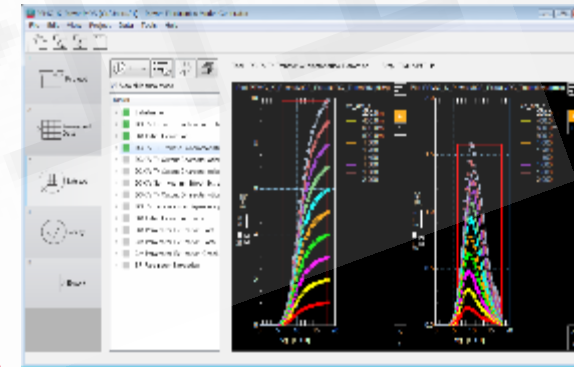


PD1500A Dynamic Power Device Analyzer/Double Pulse Tester

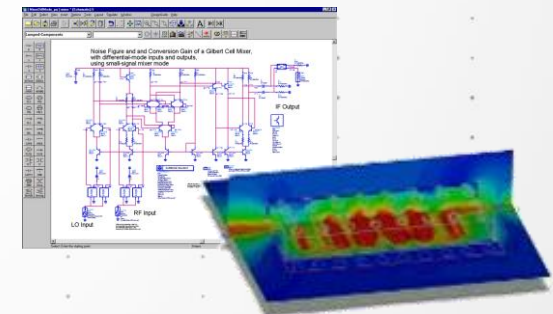
- 1.2kV/200A
- Switching parameters & high power IV derivation for modeling
- Automated and easy to use operation
- Automated thermal up to +150°C
- Modular architecture



Keysight W8598BP PEMG



Keysight ADS/EMPro



2019 第四届 是德科技感恩月活动

仪器行业最大型的线上活动!!



Q&A

微信扫码二维码
注册直播仪器抽奖

抽奖地址



一等奖：
200MHz示波器



二等奖两名：
E36311A一台

4.50221



KEYSIGHT
TECHNOLOGIES

